



Micro Commercial Components
20736 Marilla Street Chatsworth
CA 91311
Phone: (818) 701-4933
Fax: (818) 701-4939

GS2A-LT THRU GS2M-LT

Features

- For Surface Mount Applications
- Extremely Low Thermal Resistance
- Easy Pick And Place
- High Temp Soldering: 250°C for 10 Seconds At Terminals

Maximum Ratings

- Operating Temperature: -55°C to +150°C
- Storage Temperature: -55°C to +150°C
- Maximum Thermal Resistance; 20°C/W Junction To Lead

MCC Part Number	Device Marking	Maximum Recurrent Peak Reverse Voltage	Maximum RMS Voltage	Maximum DC Blocking Voltage
GS2A-LT	GS2A	50V	35V	50V
GS2B-LT	GS2B	100V	70V	100V
GS2D-LT	GS2D	200V	140V	200V
GS2G-LT	GS2G	400V	280V	400V
GS2J-LT	GS2J	600V	420V	600V
GS2K-LT	GS2K	800V	560V	800V
GS2M-LT	GS2M	1000V	700V	1000V

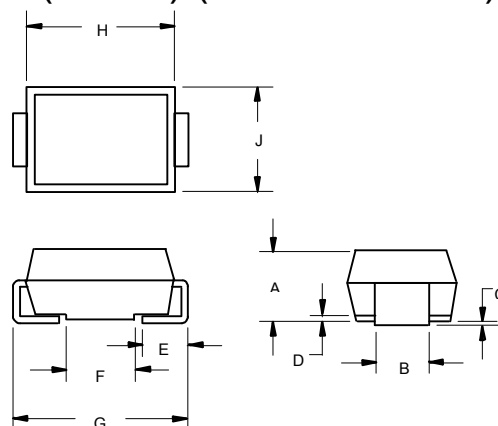
Electrical Characteristics @ 25°C Unless Otherwise Specified

Average Forward current	$I_{F(AV)}$	2.0A	$T_J = 110^\circ\text{C}$
Peak Forward Surge Current	I_{FSM}	50A	8.3ms, half sine
Maximum Instantaneous Forward Voltage	V_F	1.1V	$I_{FM} = 2.0\text{A}; T_J = 25^\circ\text{C}^*$
Maximum DC Reverse Current At Rated DC Blocking Voltage	I_R	10μA 50μA	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$
Typical Junction Capacitance	C_J	20pF	Measured at 1.0MHz, $V_R=4.0\text{V}$

*Pulse test: Pulse width 300 μsec, Duty cycle 2%

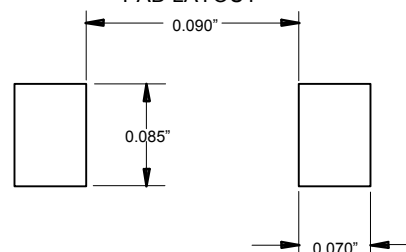
2.0 Amp Glass Passivated Rectifier 50 to 1000 Volts

DO-214AC (SMAJ) (LEAD FRAME)



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	.078	.096	2.00	2.44	
B	.055	.062	1.40	1.60	
C	.002	.008	.05	.20	
D	---	.02	---	.51	
E	.030	.060	.76	1.52	
F	.065	.091	1.65	2.32	
G	.188	.208	4.80	5.28	
H	.157	.181	4.00	4.60	
J	.098	.114	2.50	2.90	

SUGGESTED SOLDER PAD LAYOUT



GS2A-LT thru GS2M-LT



Figure 1
Typical Forward Characteristics

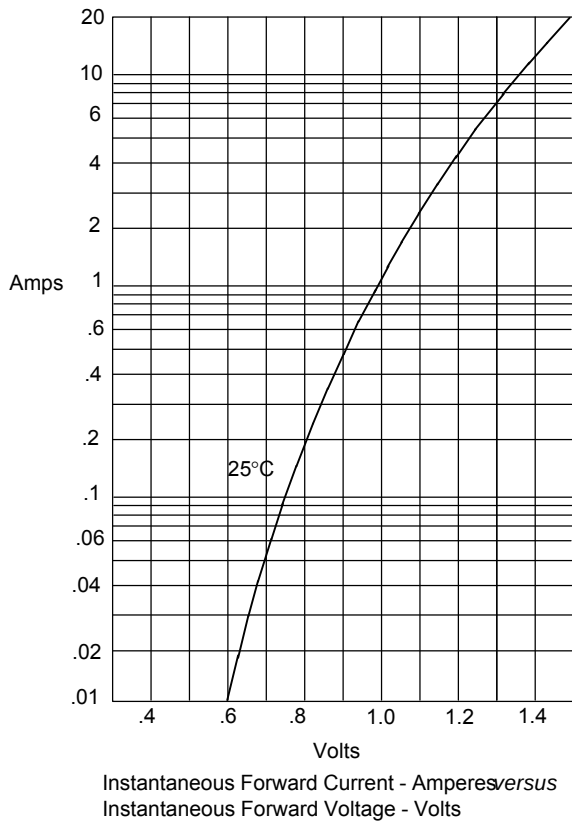


Figure 3
Maximum Overload Surge Current

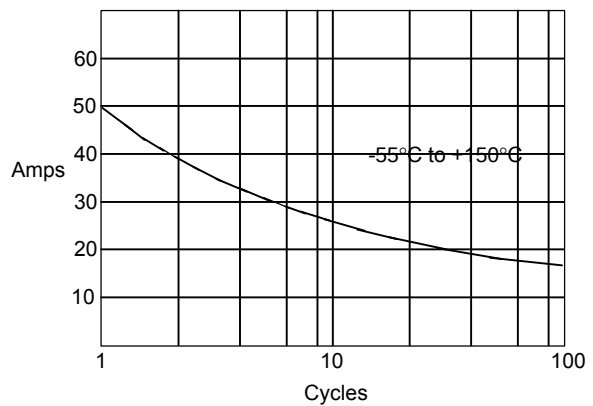


Figure 4
Forward Derating Curve

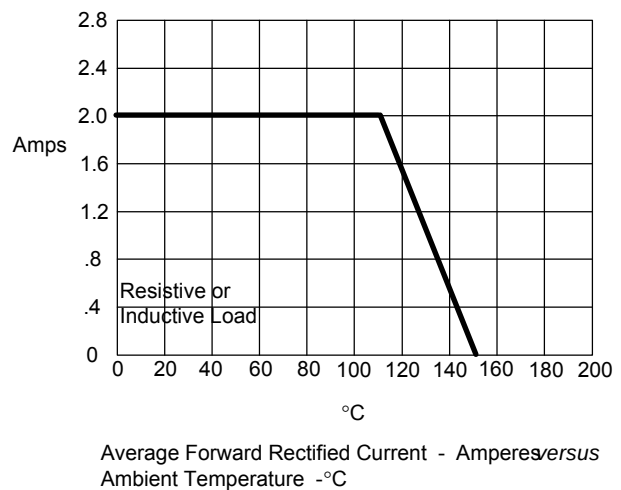
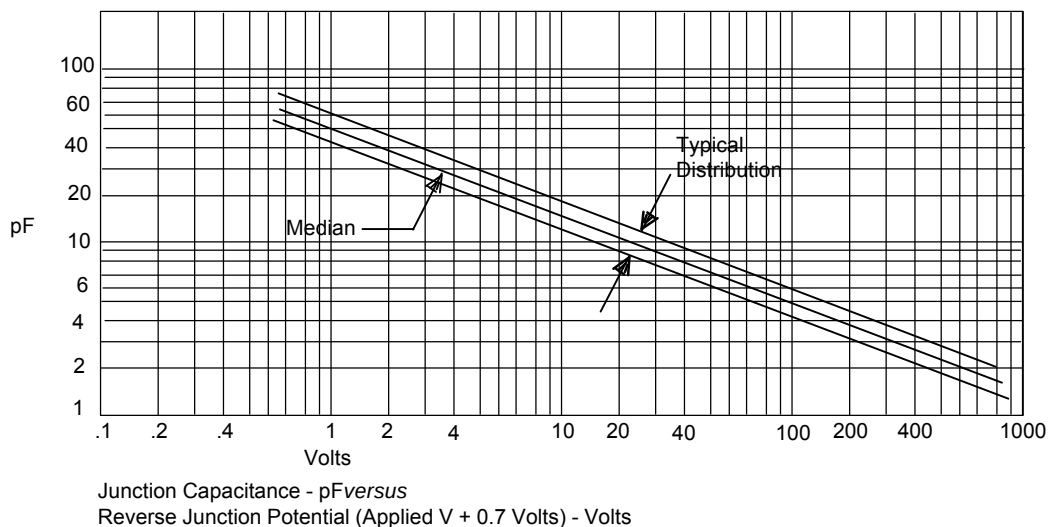
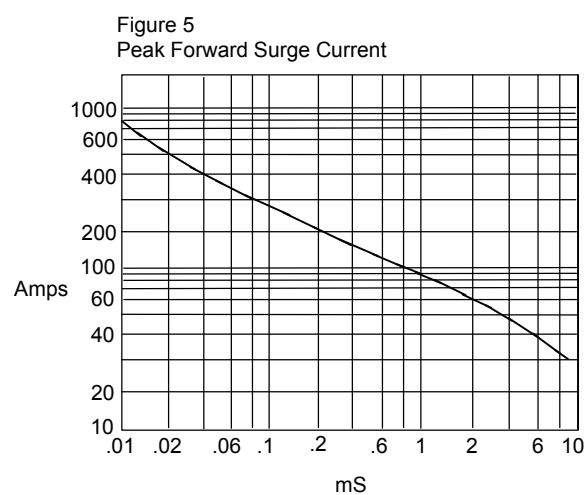


Figure 2
Junction Capacitance





Peak Forward Surge Current - Amperes *versus*
Pulse Duration - Milliseconds (mS)